



**PRINTED CIRCUIT BOARDS**  
**INTERCONNECTION CARRIERS**

State of the Art: PCB's

Revisio

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**01**

**4.11.2001**

**1/1**

**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**04 156 FR4 35 L50.35 P18\_10 S1**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**04\_156\_FR4\_35\_L50.35\_p18\_10\_s1**

Layers	in $\mu$	Material	Build-Up	Assembly
<b>Layer-1</b>	35 $\mu$	Copper		A1 B
	100 $\mu$	Prepreg	(100 $\mu$ PrePreg-Type: 2125)	
	180 $\mu$	Prepreg	(180 $\mu$ PrePreg-Type: 7628)	
	180 $\mu$	Prepreg		
<b>Layer-2</b>	35 $\mu$	Copper		
	500 $\mu$	L-FR4		
<b>Layer-3</b>	35 $\mu$	Copper		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
<b>Layer-99</b>	35 $\mu$	Copper		

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